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(12) United States Design Patent

Gouda

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(54) **LIGHT EMITTING DIODE CHIP**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

Jun. 30, 2022 (JP) ..... 2022-014086 D

(51) **LOC (14) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
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CPC H01L 27/15; H01L 27/156; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 33/48; H01L 33/483; H01L 33/486; H01L 2223/5441; H01L 2223/54433; H01L 25/167; H01L 25/0753
See application file for complete search history.

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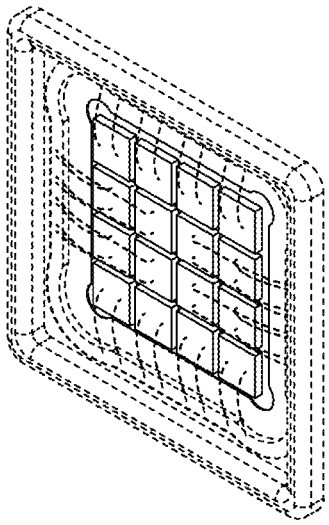
(57) **CLAIM**

The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. **1** is a front view of the light emitting diode chip;
FIG. **2** is a back view thereof;
FIG. **3** is a top view thereof, a bottom view being a mirror image of the top view;
FIG. **4** is a right side view thereof, a left side view being a mirror image of the right side view;
FIG. **5** is another front view thereof;
FIG. **6** is a cross-sectional view thereof, taken along line **6-6** in FIG. **5**; and,
FIG. **7** is a perspective view thereof.
The broken lines show environment and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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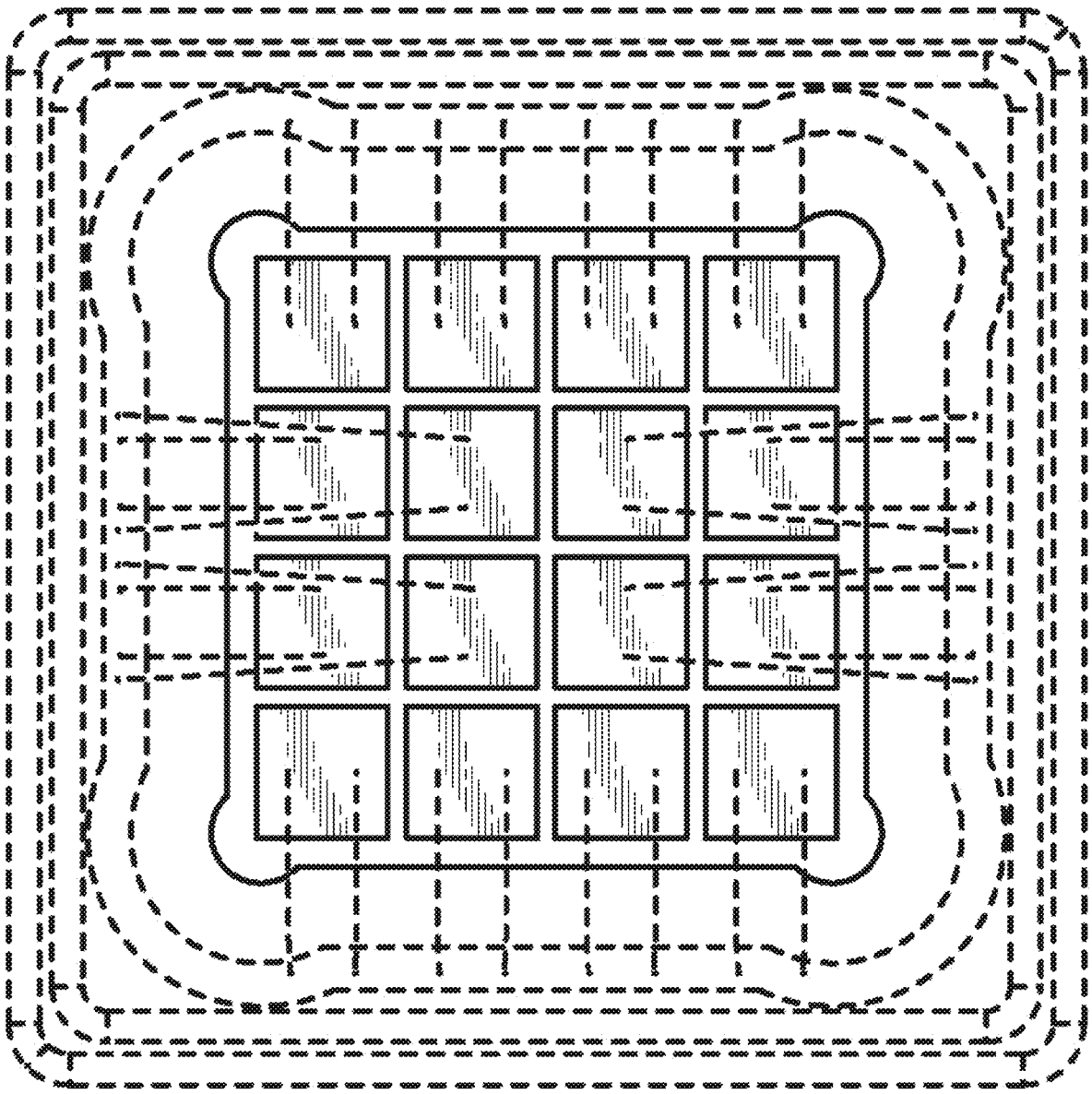


FIG. 1

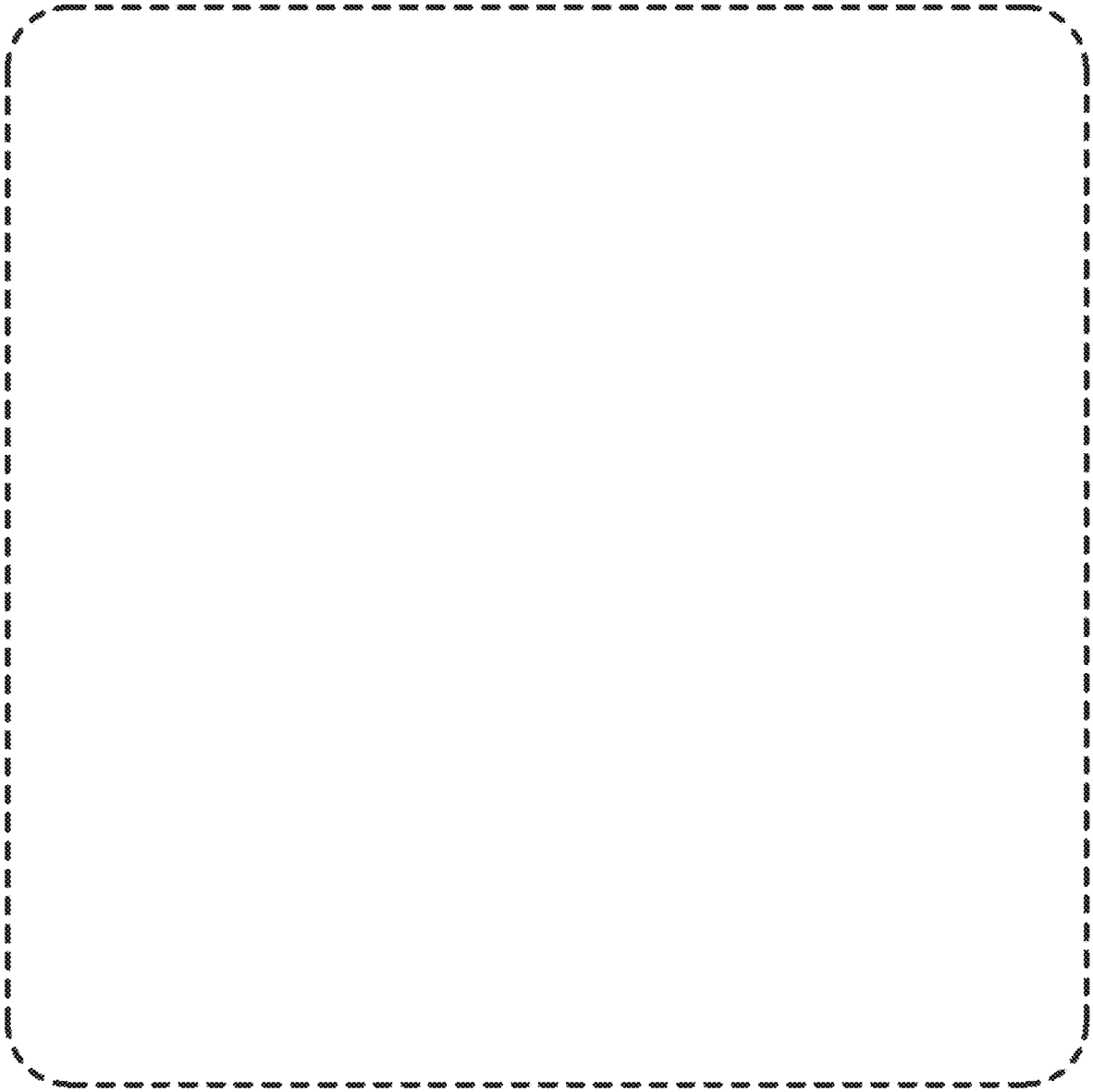
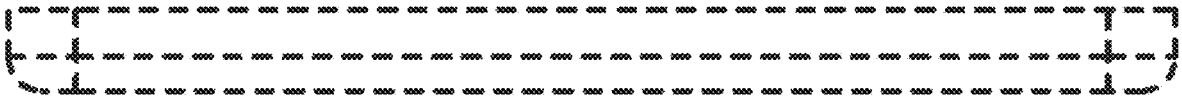


FIG. 2



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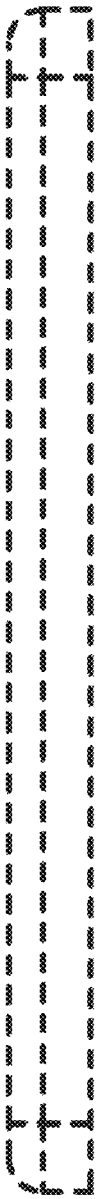

FIG. 4

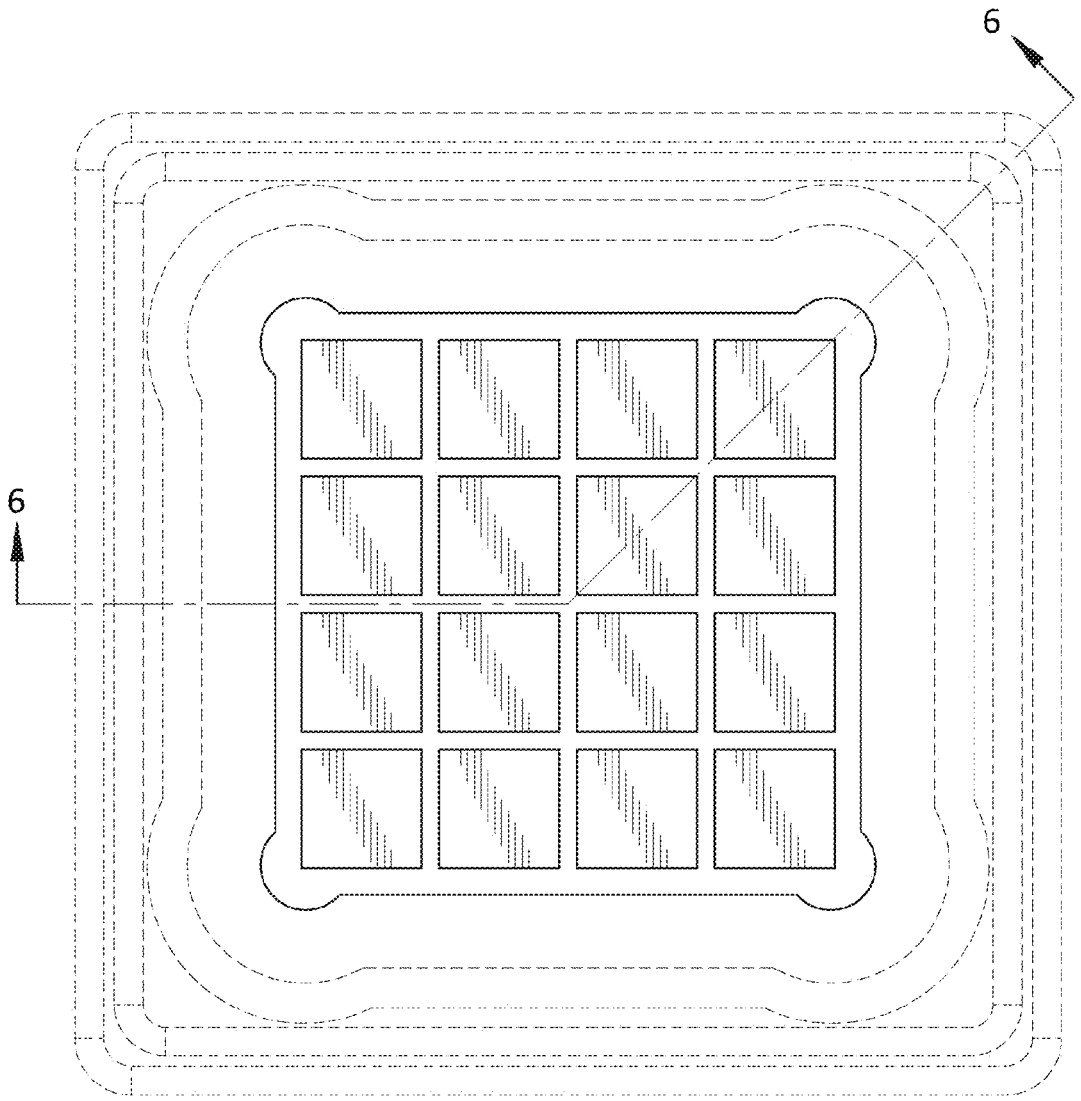

FIG. 5

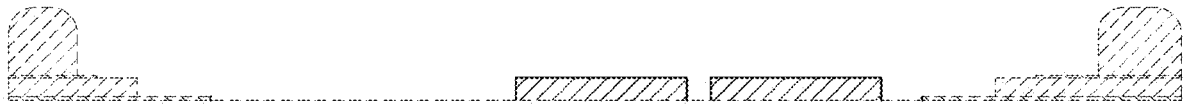

FIG. 6

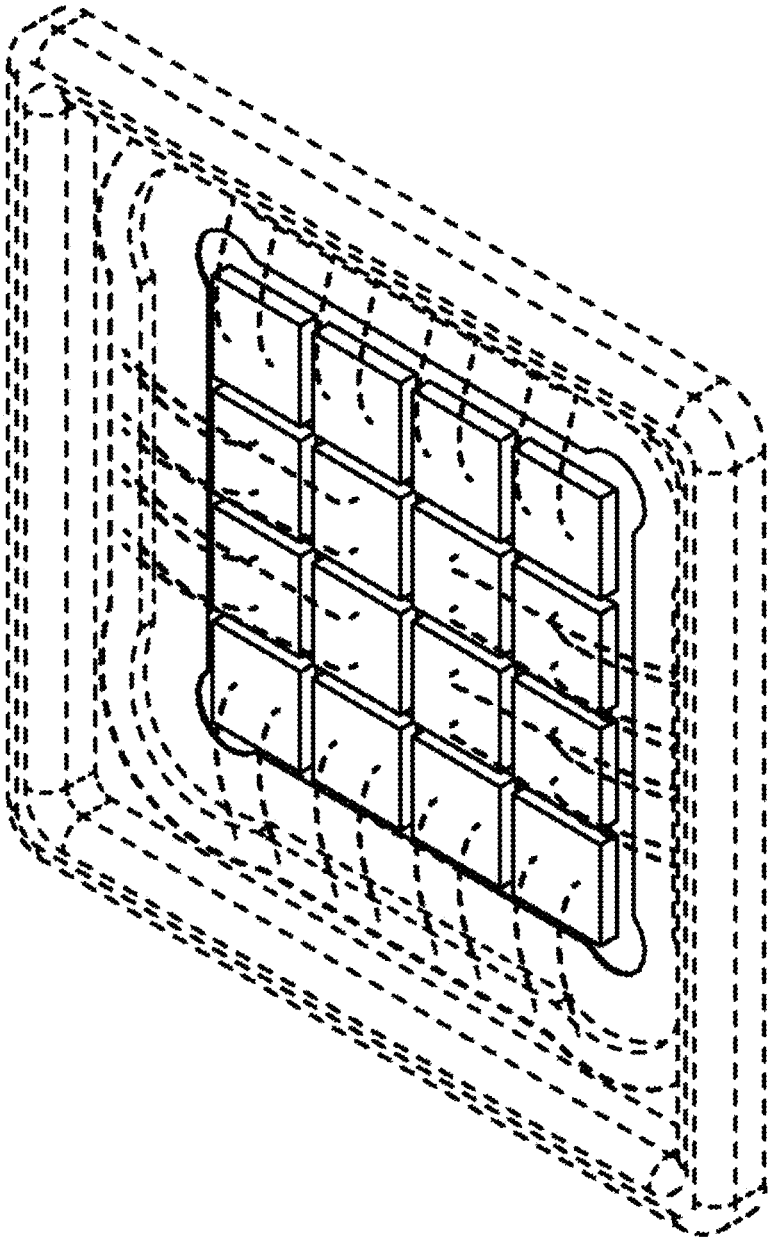

FIG. 7